



ASE Packages One Billion Bluetooth Devices for CSR

Strong partnership sees CSR benefit from ASE's technology leadership and advanced turnkey manufacturing capabilities

Santa Clara, California, June 17, 2008 – Advanced Semiconductor Engineering Incorporated (ASE, TAIEX: 2311, NYSE: ASX), the world's largest semiconductor packaging and test company, announced today that it has provided CSR with the subcontractor assembly services that facilitated the shipment of its first one billion Bluetooth devices. CSR, the leading global provider of personal wireless technology, selected ASE for consistently providing the technology and manufacturing acumen critical to the successful manufacture of Bluetooth devices.

ASE provides CSR with full turnkey services, encompassing bumping, WL CSP, BGA/Leadframe packaging, wafer probe, and final test solutions, at facilities strategically located across Asia. Through a close working relationship, ASE offers qualified packaging technologies and roadmaps that align with CSR device specifications and needs. ASE's dedicated local support teams help accelerate package development, improve time-to-market, and enhance satisfaction in line with CSR's current and evolving needs.

"CSR leads the market in Bluetooth technology and our partnership with ASE plays a significant role in our continuing success. CSR has been able to leverage ASE's industry-leading fabrication technology and manufacturing capacity to its advantage", said Patrick McNamee, VP of Process Engineering, CSR. "ASE has played an integral role in the production of our first billion devices and we look forward to an increasingly stronger partnership as we continue to meet demand in high growth areas."

"We are very proud to have packaged every single Bluetooth device which CSR has brought to market, through the successful alignment of our manufacturing strategy with CSR's product and market objectives," said Dr Tien Wu, COO, ASE Group. "Both ASE and CSR have extensive history as innovators, and together we have achieved a significant milestone, which is testament to our combined market leadership and expertise."

About ASE Group

The ASE Group is the world's largest provider of independent semiconductor manufacturing services in assembly and test. As a global leader geared towards meeting the industry's ever growing needs for faster, smaller and higher performance chips, the Group develops and offers a wide portfolio of technology and solutions including IC test program design, front-end engineering test, wafer probe, wafer bump, substrate design and supply, wafer level package, flip chip, system-in-package, final test and electronic manufacturing services through Universal Scientific Industrial Co Ltd, a member of the ASE Group. The Group generated sales revenues of \$3.1 billion in 2007 and employs over 28,000 people worldwide. For more information about the ASE Group, visit www.aseglobal.com.

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